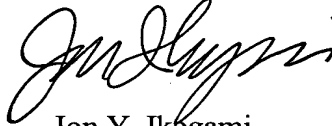


REMARKS

Figures 1A and 2A have been amended to remove the unnumbered arrows from solder ball 250, change the dotted lines of UBM layer 240 into solid lines, and overall create a more accurate reflection of the solder bump pictured. No new matter has been added.

Applicant believes that all pending claims are allowable and respectfully requests a Notice of Allowance for this application from the Examiner. Should the Examiner believe that a telephone conference would expedite the prosecution of this application, the undersigned can be reached at the telephone number set out below.

Respectfully submitted,
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